



China Semiconductor Technology International Conference (CSTIC) 2020 Summary

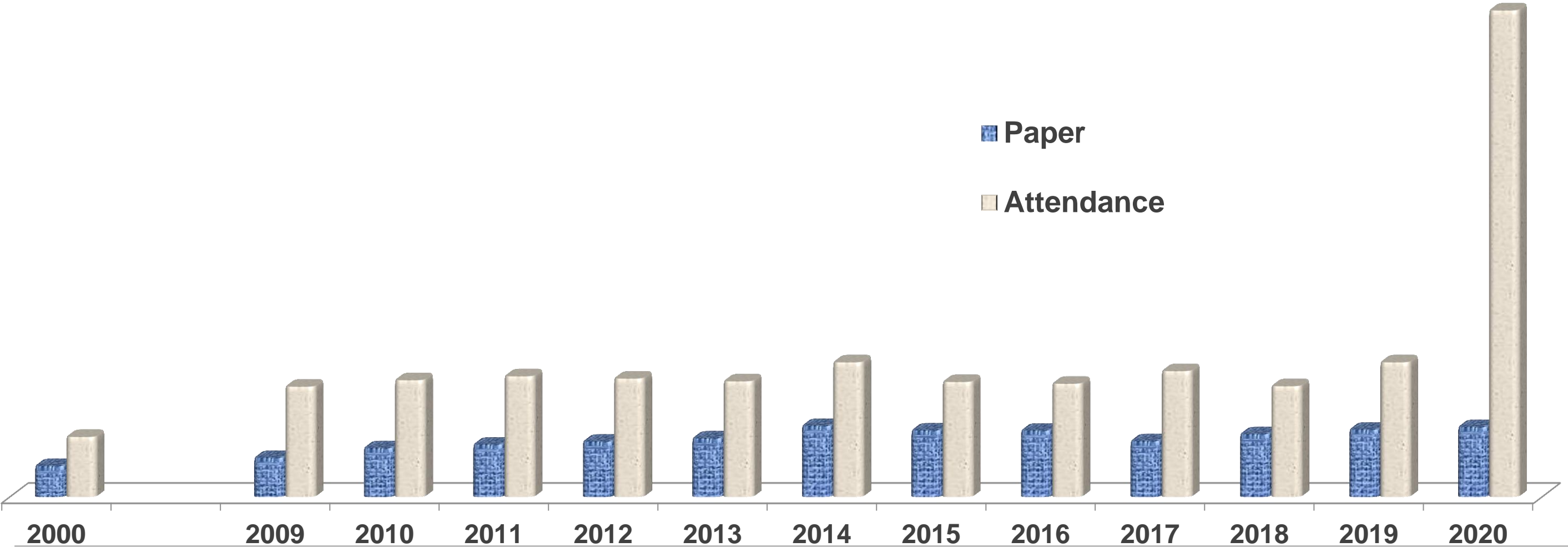
June 26-July 24

SEMICON[®] CHINA

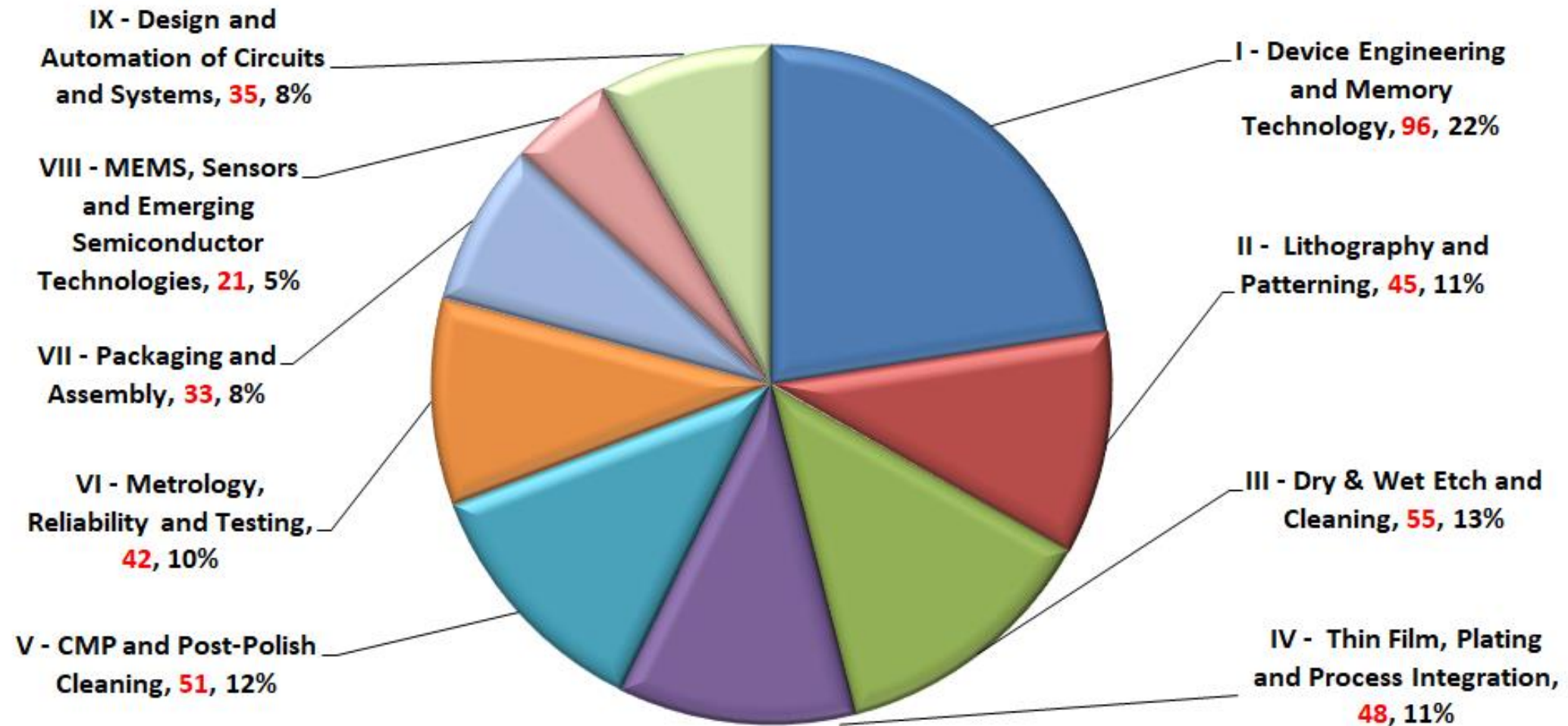


2020 CSTIC - First Online Virtual Conference

- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- Record-breaking 430 abstracts, 2746 attendees, and 12630 clicks at v.semi.org.cn



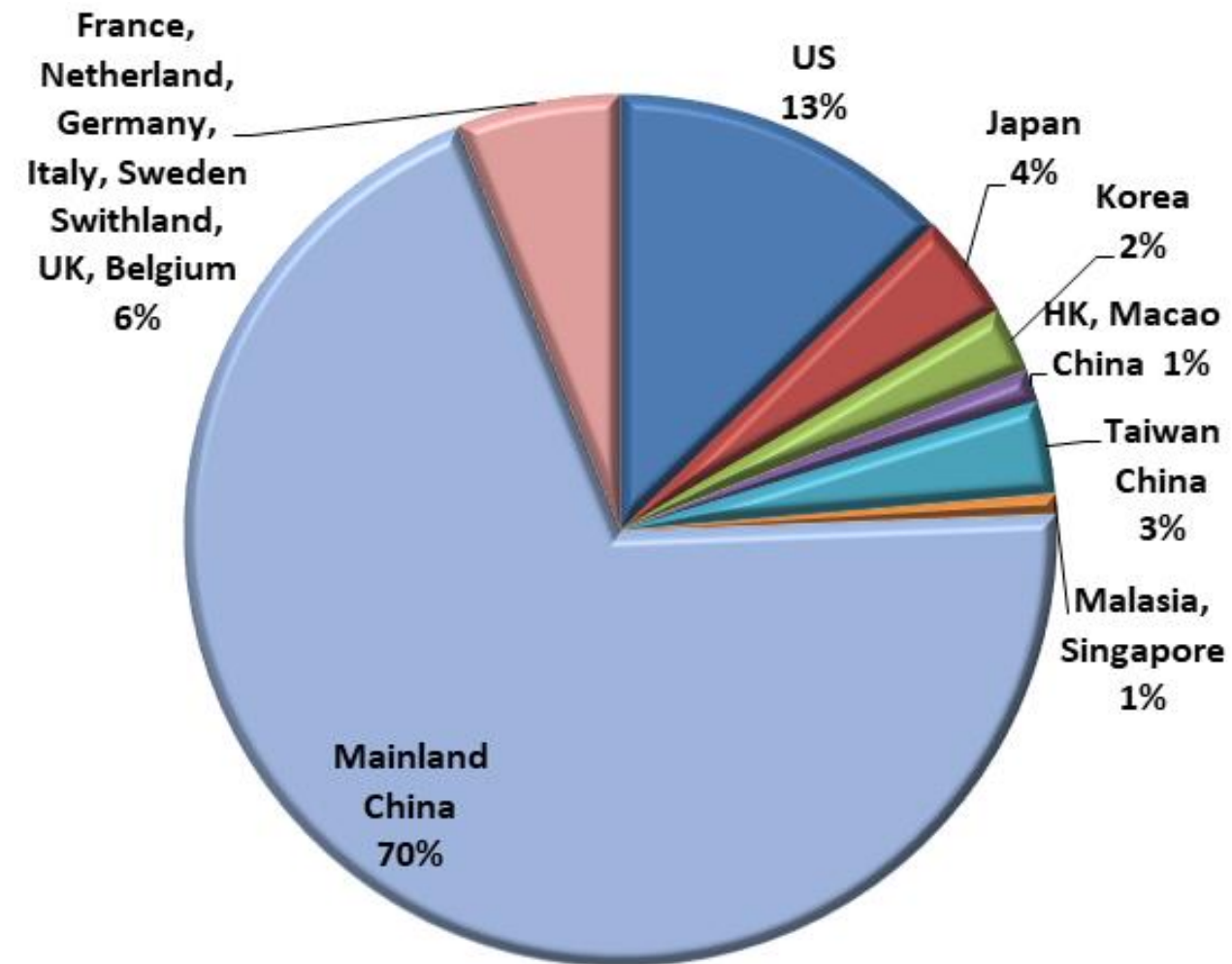
CSTIC Symposium Platform



220 Full-Length Manuscripts Published in IEEE Xplore (*EI* cited)

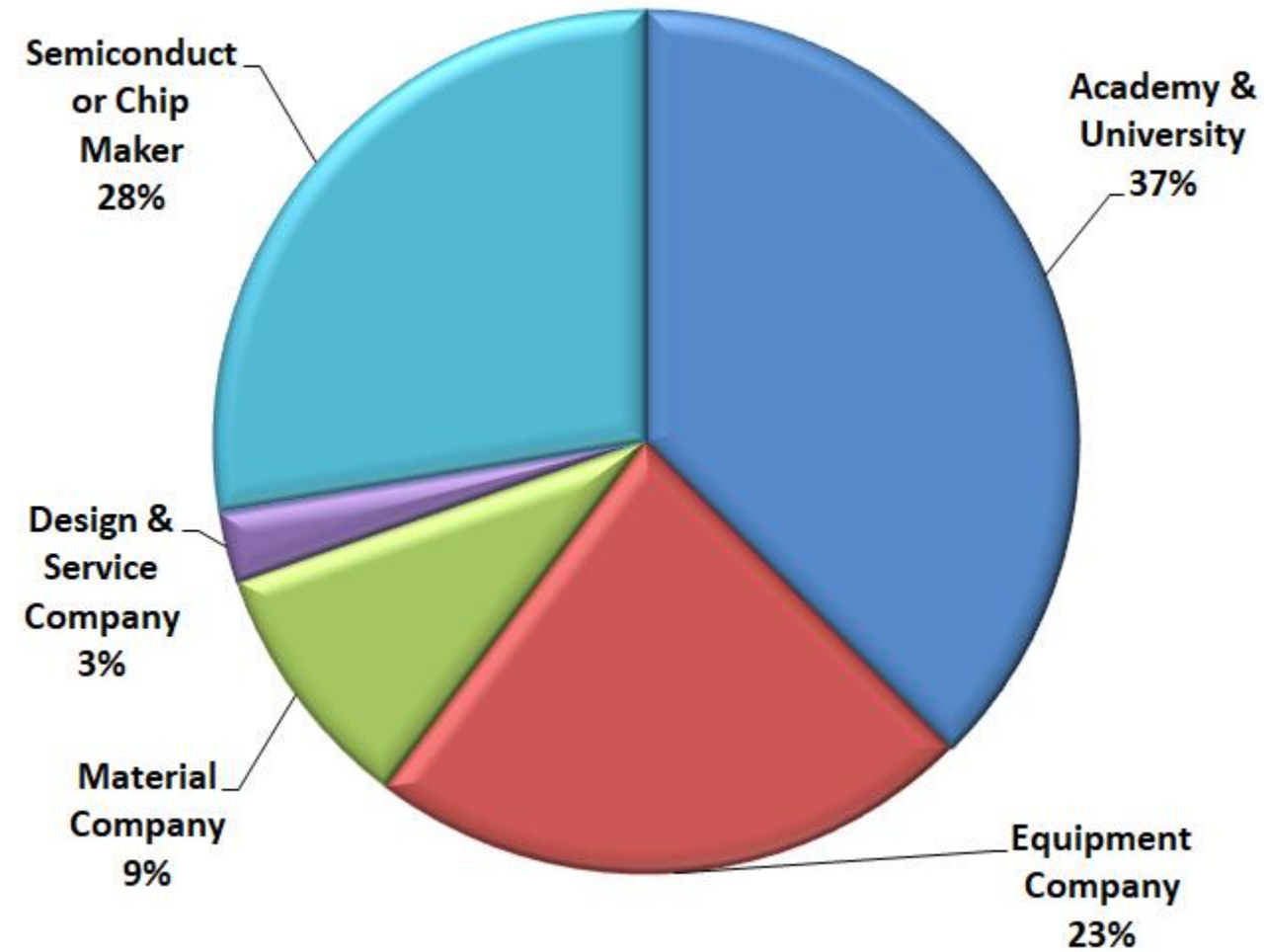
International Collaboration

- **430** submissions from **17** countries and regions



Industry Collaboration

- **63%** abstracts from industry



Registration Worldwide

2746 registration from **20** countries and regions



Belgium
Canada
China Hong Kong
China Macau
China Mainland
China Taiwan Region
Finland
France
Germany
Italy
Japan
Korea
Malaysia
Netherlands
Singapore
South Africa
Sweden
Switzerland
United Kingdom
United States of America

Plenary Keynotes



Next Big Frontiers - Chiplet Integration and More

Dr. Doug Yu
Vice President, R&D, TSMC



Opportunities in Advanced Packaging for Heterogeneous Integration

Dr. Ravi Mahajan
Fellow, Intel



EUV Lithography - the Road to High-Volume Manufacturing

Dr. Anthony Yen
Vice President, ASML





Integrated Materials Solutions: A Path Forward For Moore's Law

Dr. Sanjay Natarajan
Vice President,
Applied Materials

Conference Schedule

Poster Session: June 26-July 24 **156 posters**
Tutorials: June 28-July 24 **5 tutorials**
Plenary Session,9 Symposia and Panel Discussion **157 videos**

- Symp I: Device Engineering and Memory Technology
- Symp. II: Lithography and Patterning
- Symp. III: Dry &Wet Etch and Cleaning
- Symp. IV: Thin Film, Plating and Process Integration
- Symp. V: CMP and Post-Polish Cleaning
- Symp. VI: Metrology, Reliability and Testing
- Symp. VII: Packaging and Assembly
- Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies
- Symp. IX: Design and Automation of Circuits and Systems

	<p>Dr. Tak H. Ning</p> <p>Fellow, IBM</p>		<p>Dr. Anabela Veloso</p> <p>Principal Member of Technical Staff, IMEC</p>
	<p>Dr. Jean-Charles Barbé</p> <p>Chief Scientist, CEA-LETI</p>		<p>Dr. Dechao Guo</p> <p>Senior Manager, Advanced Device Research, IBM Research</p>
	<p>Prof. Stacey F. Bent</p> <p>Professor, Stanford University</p>		<p>Dr. AbdelKarim Mercha</p> <p>Technical Director, IMEC</p>
	<p>Prof. Shawn Blanton</p> <p>Professor, CarnegieMellon University</p>	 <p>CSTIC 2020</p> <p>中国半导体技术大会</p>	
	<p>Dr. Hakaru Mizoguchi</p> <p>Exective Vice President and CTO, Gigaphoton</p>		<p>Mr. Terrance Lee</p> <p>Vice President, Applied Materials</p>
	<p>Dr. Jonathan Reid</p> <p>Fellow, Lam Research</p>		<p>Dr. Hu Chuan</p> <p>Chief Expert, Guangdong Academy of Sciences</p>
	<p>Dr. Bill Bottoms</p> <p>Chairman & CEO, 3MTS</p>		<p>Dr. Jeongdong Choe</p> <p>Senior Technical Fellow, Technisights</p>
	<p>Prof. Vijaykrishnan Narayanan</p> <p>Distinguished Professor, Pennsylvania State University</p>		<p>Prof. Hidetoshi Onodera</p> <p>Professor, Kyoto University</p>
			

Panel Discussion: System Integration through 3D and Advanced Packaging



Moderator: Dr. Steve X. Liang

1. We understand that 3D heterogeneous integration will help extend Moore's law from systems' perspective. Will it be a short-term boost or continuous enhancement node after node?
2. What are the key features for 3D and Advance Packaging Integration, TSV pitch, Chip Layers, etc? How small these critical pitches can go and is there a trend like Moore's law to follow?
3. 3D package vs. 3D sequential integration comparison in terms of thermal budgets, performance, power management, etc.
4. What are the impacts of the 3D and Advance Packaging Integration to the existing OSAT business and supply chains? What are the major opportunities for the existing OSAT business?

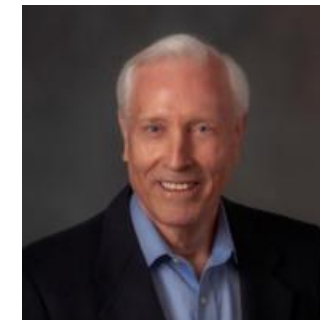
Panelists



Dr. Doug Yu
Vice President, R&D, TSMC



Dr. Ravi Mahajan
Fellow, Intel



Dr. Bill Bottoms
CEO, 3MTS

Tutorials

1. Advanced Memory Technologies: MRAM



Dr. Shu-Jen Han
Senior Director
HFC Semiconductor Corp.

2. Advanced Memory Technologies: EPCM/3D-PCM



Dr. Yu Zhu
Executive Assistant to CEO,
Jiangsu Advanced Memory Semiconductor (AMS) Co., Ltd

3. Semiconductor Testing Solutions in the Trend of 5G and AI



Liang Ge
R&D manager and Test strategy leader
Advantest China

4. Heterogeneous Integration And Advanced Packaging



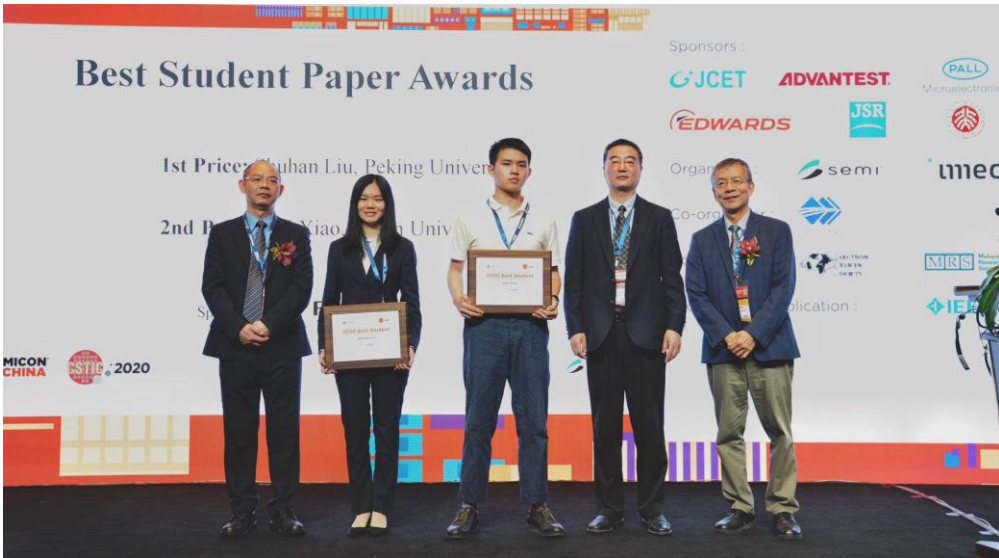
Dr. Bill Bottoms
Chairman and CEO, 3MTS

5. IC Reliability Tests For 5G Applications



Xu Feng
Deputy General Manager & Technology Director
JCET quality test center

Plenary Session and Award Winners



Conference Chair and Co-Chairs



Dr. Steve X. Liang
Chair
JCET, China



Dr. Qinghuang Lin
Exe. Co-Chair
Lam, USA



Dr. Ru Huang
Co-Chair
PKU, China



Dr. Cor Claeys
Co-Chair
KU Leuven,
Belgium



Dr. Hanming Wu
Co-Chair
Zhejiang University
China

Symposium Chairs



Dr. Ru Huang
Chair, S-I
Peking Univ.
China



Dr. Kafai Lai
Chair, S-II
IBM
USA



Dr. Ying Zhang
Chair, S-III
Naura
USA



Dr. Beichao
Zhang
Chair, S-IV
HFC. China



Dr. Xin Ping Qu
Chair, S-V
Fudan Univ.
China



Dr. Peilin Song
Chair, S-VI
IBM
USA



Dr. Steve X.
Liang
Chair, S-VII
JCET, China



Dr. Qinghuang
Lin
Chair, S-VIII
Lam, USA

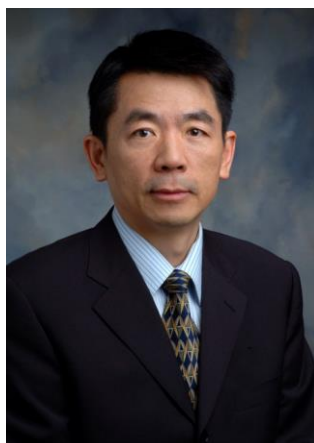


Dr. Wenjian Yu
Chair S-IX
Tsinghua
University,
China



Dr. Hsiang-Lan
Lung
Poster Chair
Macronix,
Taiwan, China

Organizing Team



Mr. Lung Chu
President
SEMI China

Ms. Lily Feng
Ms. April Peng
Ms. Cheryl Qiu
Ms. Mina Chen
Mr. Tony Liu

Mr. Jesse Zhang
Ms. June Wu
Mr. Mortal Li
Ms. Hannah Zhao
Ms. Louisa Li

SEMI China Team



Dr. Lode Lauwers
Vice President
IMEC, Belgium

Special Thanks to Sponsors



CSTIC 2021

- Time: March 14-15 (Sunday-Monday)
- Venue: Shanghai International Convention Center (SHICC)
- Call for Papers Deadline: Nov. 15, 2020





Thanks for the Support!

